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Should be replaced with:

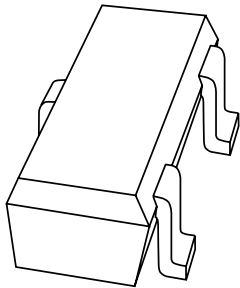
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DATA SHEET



2PB709AW

PNP general purpose transistor

Product data sheet

2002 Jun 26

PNP general purpose transistor

2PB709AW

FEATURES

- High collector current (max. 100 mA)
- Low collector-emitter saturation voltage (max. 500 mV).

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

PNP transistor in an SC-70 (SOT323) plastic package.
NPN complement: 2PD601AW

MARKING

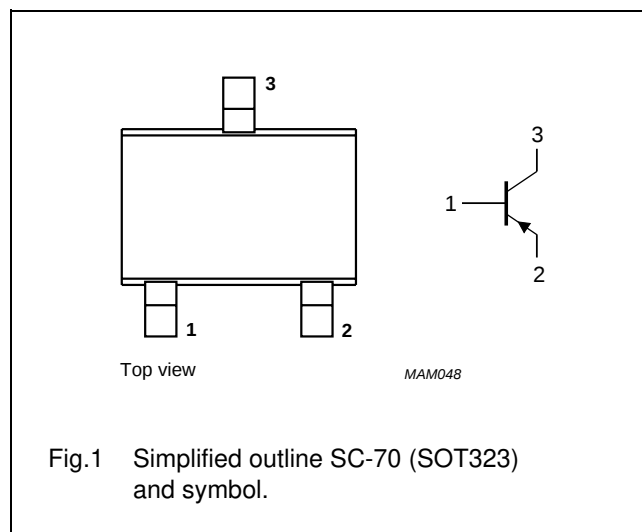
TYPE NUMBER	MARKING CODE ⁽¹⁾
2PB709AQW	N5*
2PB709ARW	N7*
2PB709ASW	N9*

Note

1. * = p: made in Hong Kong.
* = t: made in Malaysia.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–45	V
V_{CEO}	collector-emitter voltage	open base	–	–45	V
V_{EBO}	emitter-base voltage	open collector	–	–6	V
I_C	collector current (DC)		–	–100	mA
I_{CM}	peak collector current		–	–200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	200	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. For mounting conditions, see “Thermal considerations and footprint design for SOT323 in the General Part of Data Handbook SC18”.

PNP general purpose transistor

2PB709AW

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	625	K/W

Note

- For mounting conditions, see “Thermal considerations and footprint design for SOT323 in the General Part of Data Handbook SC18”.

CHARACTERISTICS

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$I_E = 0; V_{CB} = -45\text{ V}$	–	–10	nA
		$I_E = 0; V_{CB} = -45\text{ V}; T_j = 150\text{ °C}$	–	–5	μA
I_{EBO}	emitter-base cut-off current	$I_C = 0; V_{EB} = -5\text{ V}$	–	–10	nA
h_{FE}	DC current gain 2PB709AQW 2PB709ARW 2PB709ASW	$I_C = -2\text{ mA}; V_{CE} = -10\text{ V}$	160 210 290	260 340 460	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -100\text{ mA}; I_B = -10\text{ mA};$ note 1	–	–500	mV
C_c	collector capacitance	$I_E = I_E = 0; V_{CB} = -10\text{ V};$ $f = 1\text{ MHz}$	–	5	pF
f_T	transition frequency 2PB709AQW 2PB709ARW 2PB709ASW	$I_C = -1\text{ mA}; V_{CE} = -10\text{ V};$ $f = 100\text{ MHz}$	60 70 80	– – –	MHz MHz MHz

Note

- Pulse test: $t_p \leq 300\text{ μs}$; $\delta \leq 0.02$.

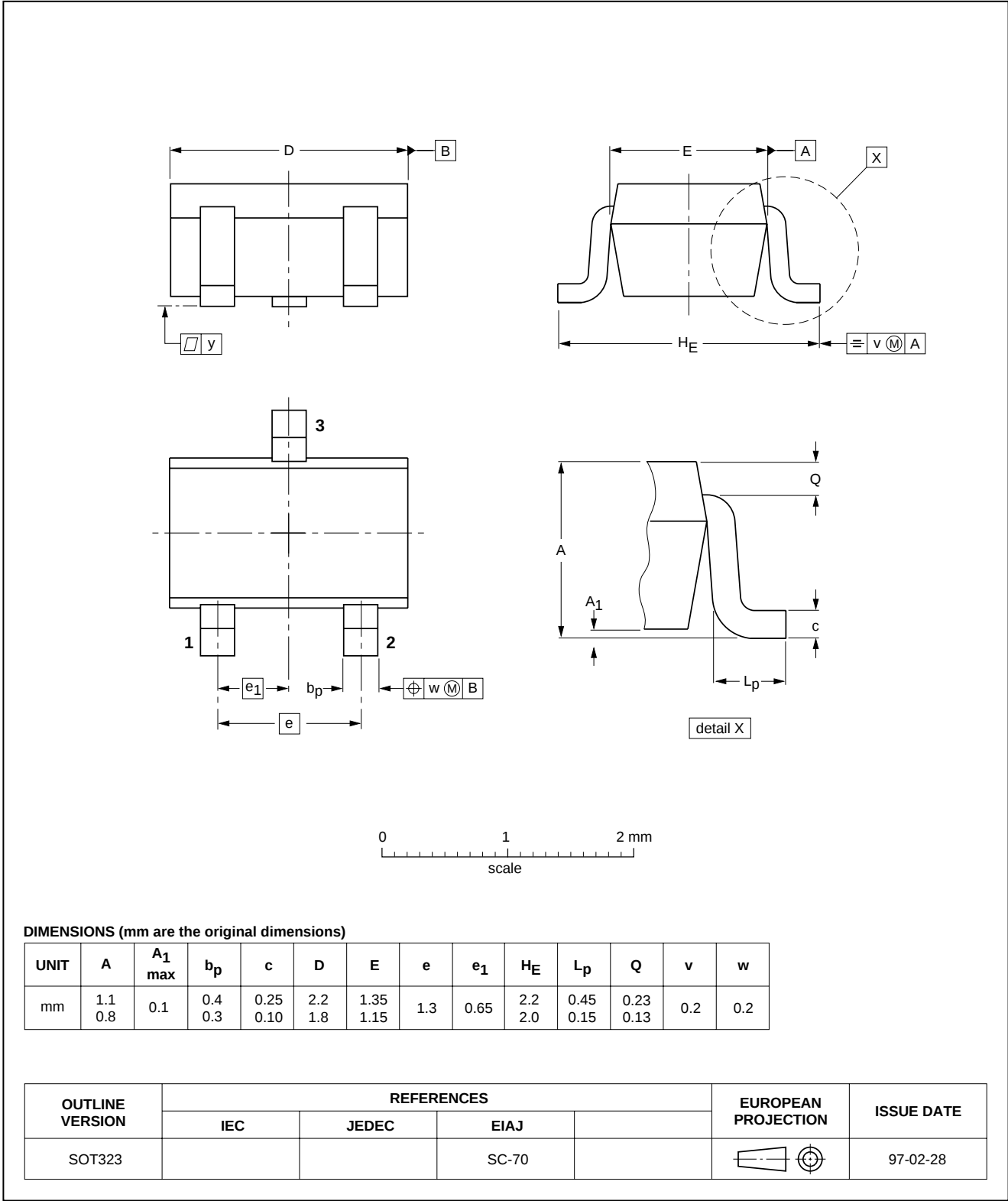
PNP general purpose transistor

2PB709AW

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT323



PNP general purpose transistor

2PB709AW

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

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Printed in The Netherlands

613514/01/pp6

Date of release: 2002 Jun 26

Document order number: 9397 750 09758

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